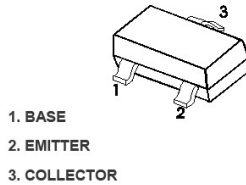


SOT-23

Marking: 3G
特征 Features

- Power Dissipation of 200mW
- Ideally suited for automatic insertion
- For switching and AF amplifier applications

机械数据 Mechanical Data

- Small Outline Plastic Package
- Epoxy UL: 94V-0
- Mounting Position: Any

极限值和温度特性(TA = 25°C 除非另有规定)

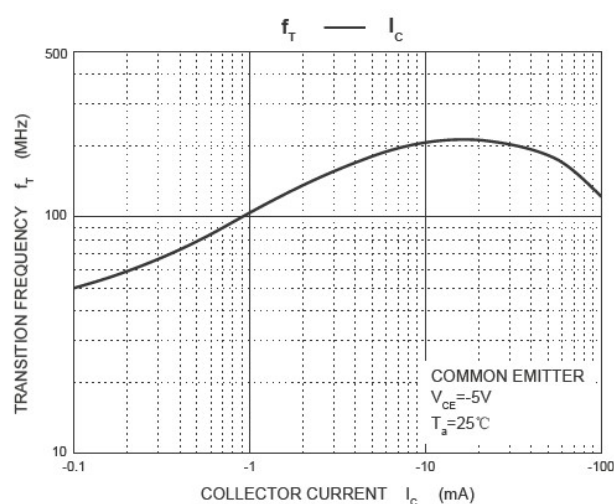
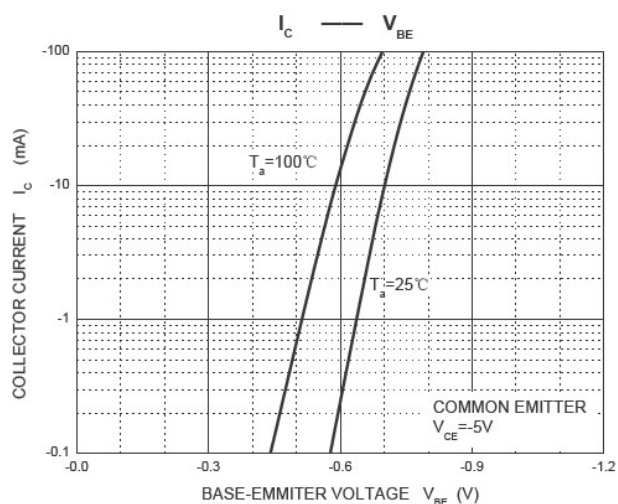
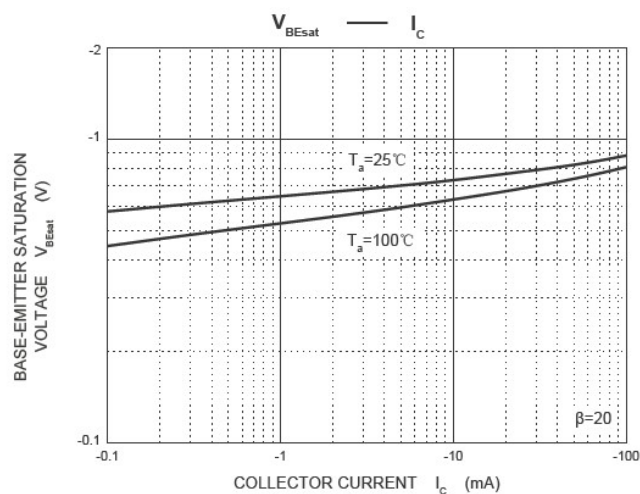
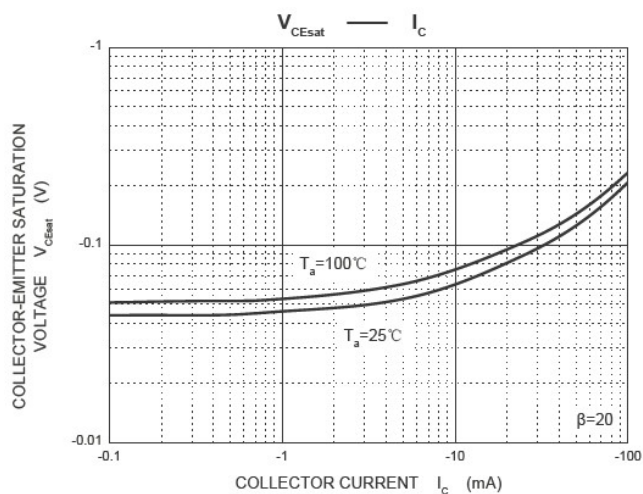
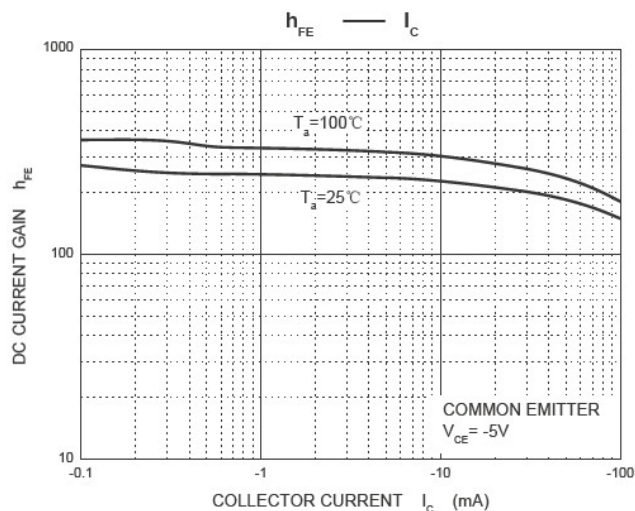
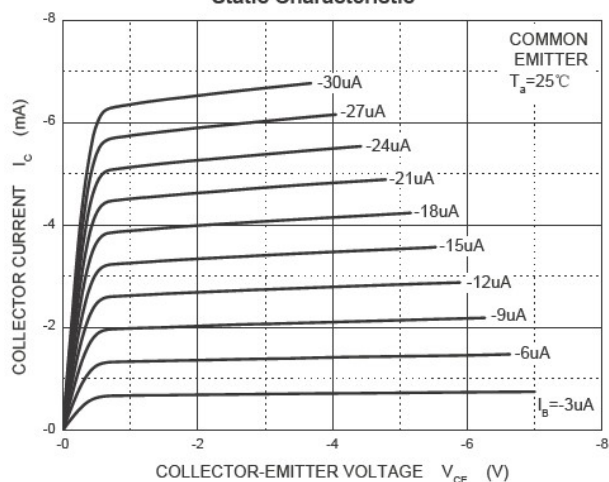
Maximum Ratings & Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

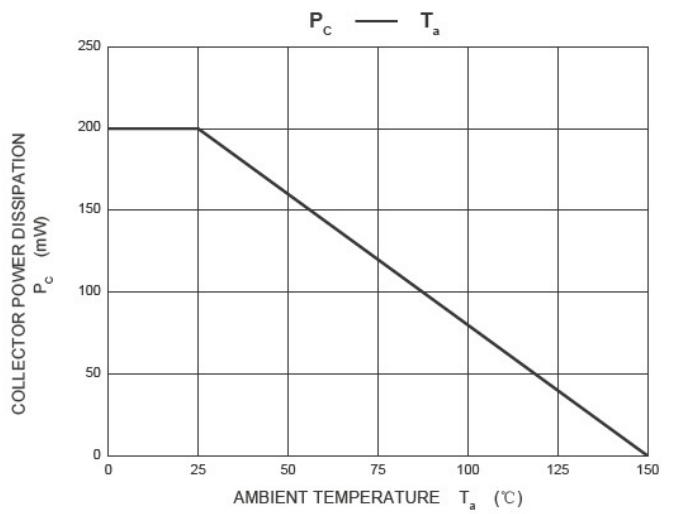
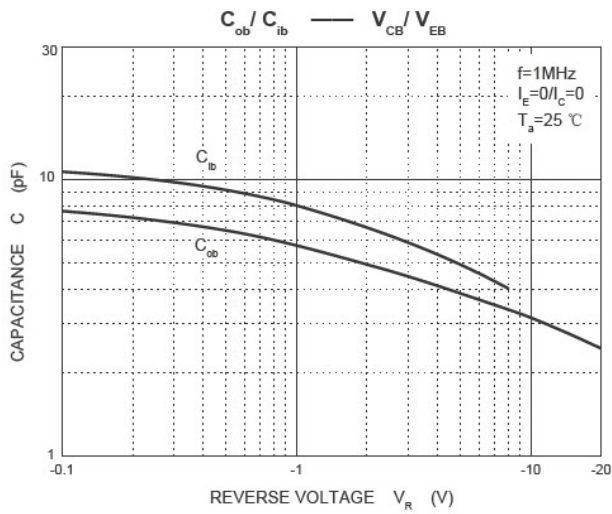
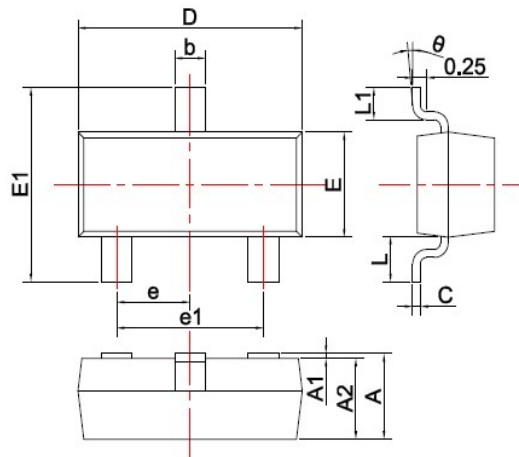
参数 Parameters	符号 Symbol	数值 Value	单位 Unit
Collector-Base Voltage	V _{CBO}	-50	V
Collector-Emitter Voltage	V _{CEO}	-45	V
Emitter -Base Voltage	V _{EBO}	-6	V
Collector Current-Continuous	I _C	-100	mA
Collector Power Dissipation	P _C	200	mW
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55-+150	°C
Thermal resistance From junction to ambient	R _{θJA}	625	°C/W

电特性 (TA = 25°C 除非另有规定)

Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified).

参数 Parameter	符号 Symbols	测试条件 Test Condition	界限 Limits		单位 Unit
			Min	Max	
Collector-base breakdown voltage	V _{(BR)CBO}	I _C =-10uA, I _E =0	-50		V
Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C =-10mA, I _B =0	-45		V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E =10uA, I _C =0	-6		V
Collector cut-off current	I _{CBO}	V _{CB} =-45V, I _E =0		-100	nA
Collector cut-off current	I _{CEO}	V _{CE} =-40V, I _B =0		-100	nA
Emitter cut-off current	I _{EBO}	V _{EB} =-5V, I _C =0		-100	nA
DC current gain	h _{FE}	V _{CE} =-5V, I _C =-2mA	420	800	
Collector-emitter saturation voltage	V _{CE(sat)}	I _C =-100mA, I _B =-5mA		-0.50	V
Base -emitter saturation voltage	V _{BE(sat)}	I _C =-100mA, I _B =-5mA		-1.10	V
Transition frequency	f _T	V _{CE} =-5V, I _C =-10mA, f=100MHz	100		MHz
Collector output capacitance	C _{ob}	V _{CB} =-10V, f=1MHz		4.5	pF

Typical characteristics
Static Characteristic


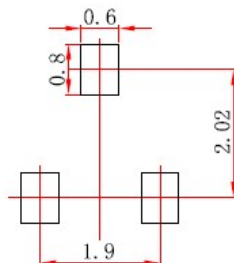

SOT-23 PACKAGE OUTLINE Plastic surface mounted package


SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

Unit: mm

焊盘设计参考Precautions: PCB Design

Recommended land dimensions for SOT-23 diode. Electrode patterns for PCBs


Note:

1. Controlling dimension: In millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

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